MC74AC139, MC74ACT139

Dual 1-of-4 Decoder/Demultiplexer

The MC74AC139/74ACT139 is a high–speed, dual 1–of–4 decoder/demultiplexer. The device has two independent decoders, each accepting two inputs and providing four mutually–exclusive active–LOW outputs. Each decoder has an active–LOW Enable input which can be used as a data input for a 4–output demultiplexer. Each half of the MC74AC139/74ACT139 can be used as a function generator providing four minterms of two variables.

- Multifunctional Capability
- Two Completely Independent 1–of–4 Decoders
- Active LOW Mutually Exclusive Outputs
- Outputs Source/Sink 24 mA
- ′ACT139 Has TTL Compatible Inputs

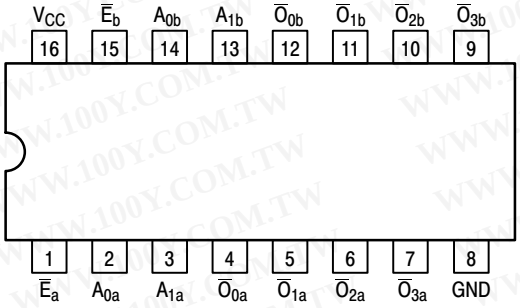

Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
A_0, A_1	Address Inputs
$\overline{E}$	Enable Inputs
$\overline{O}_0$–$\overline{O}_3$	Outputs

TRUTH TABLE

Inputs			Outputs			
$\overline{E}$	A_0	A_1	$\overline{O}_0$	$\overline{O}_1$	$\overline{O}_2$	$\overline{O}_3$
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	H	L	H	L	H	H
L	L	H	H	H	L	H
L	H	H	H	H	H	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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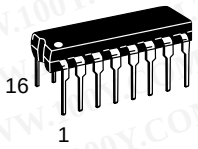
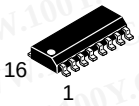
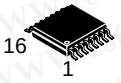


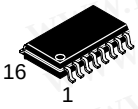
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC139N	PDIP–16	25 Units/Rail
MC74ACT139N	PDIP–16	25 Units/Rail
MC74AC139D	SOIC–16	48 Units/Rail
MC74ACT139D	SOIC–16	48 Units/Rail
MC74AC139DR2	SOIC–16	2500 Tape & Reel
MC74ACT139DR2	SOIC–16	2500 Tape & Reel
MC74AC139DT	TSSOP–16	96 Units/Rail
MC74ACT139DT	TSSOP–16	96 Units/Rail
MC74AC139DTR2	TSSOP–16	2500 Tape & Reel
MC74AC139M	EIAJ–16	50 Units/Rail
MC74ACT139M	EIAJ–16	50 Units/Rail
MC74AC139MEL	EIAJ–16	2000 Tape & Reel
MC74ACT139MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

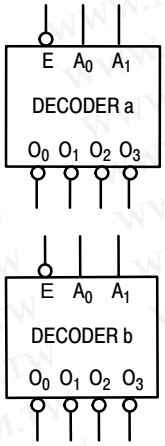
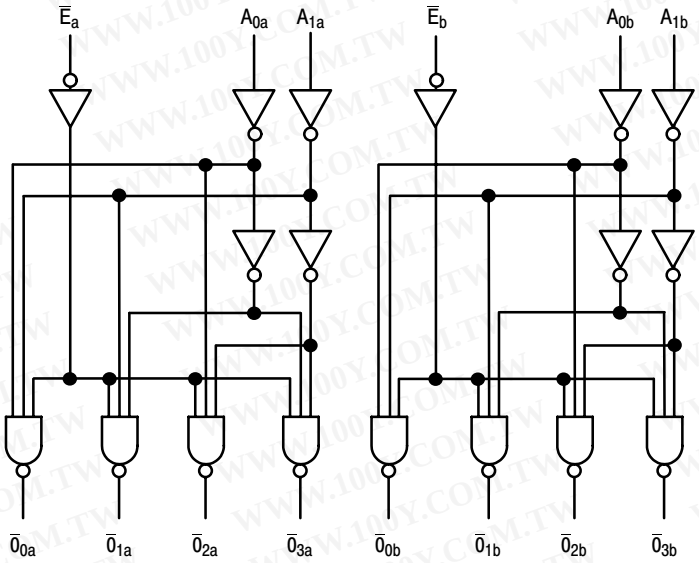


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

FUNCTIONAL DESCRIPTION

The MC74AC139/74ACT139 is a high–speed dual 1–of–4 decoder/demultiplexer. The device has two independent decoders, each of which accepts two binary weighted inputs (A_0–A_1) and provides four mutually exclusive active–LOW outputs ($\overline{O}_0$–$\overline{O}_3$). Each decoder has an active–LOW enable ($\overline{E}$). When $\overline{E}$ is HIGH all outputs are forced HIGH. The enable can be used as the data input for a 4–output demultiplexer application. Each half of the MC74AC139/74ACT139 generates all four minterms of two variables. These four minterms are useful in some applications, replacing multiple gate functions as shown in Figure 4, and thereby reducing the number of packages required in a logic network.

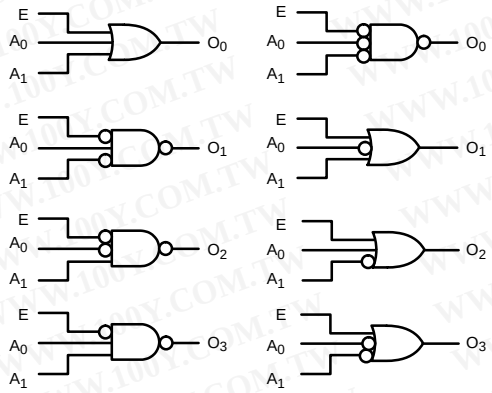


Figure 4. Gate Functions (Each Half)

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C Typ	74AC T_A = +25°C Guaranteed Limits	74AC T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF Min	74AC T_A = +25°C, C_L = 50 pF Typ	74AC T_A = +25°C, C_L = 50 pF Max	74AC T_A = –40°C to +85°C, C_L = 50 pF Min	74AC T_A = –40°C to +85°C, C_L = 50 pF Max	Unit	Fig. No.
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	4.0 3.0	8.0 6.5	11.5 8.5	3.5 2.5	13 9.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	3.0 2.5	7.0 5.5	10 7.5	2.5 2.0	11 8.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	3.3 5.0	4.5 3.5	9.5 7.0	12 8.5	3.5 3.0	13 10	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	3.3 5.0	4.0 2.5	8.0 6.0	10 7.5	3.0 2.5	11 8.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C Typ	74ACT T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF Min	Typ	Max	74ACT T_A = –40°C to +85°C, C_L = 50 pF Min	Max	Unit	Fig. No.
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	6.0	8.5	1.5	9.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	6.0	9.5	1.5	10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	5.0	2.5	7.0	10.0	2.0	11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

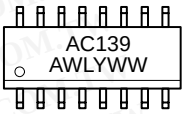
CAPACITANCE

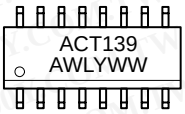
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	40	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

DIP–16

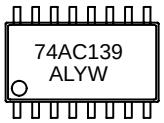
SO–16

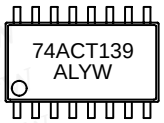




TSSOP–16

EIAJ–16

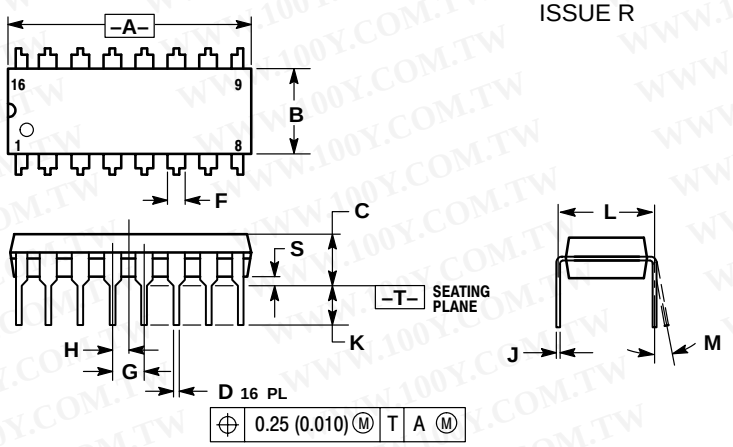




A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

PACKAGE DIMENSIONS

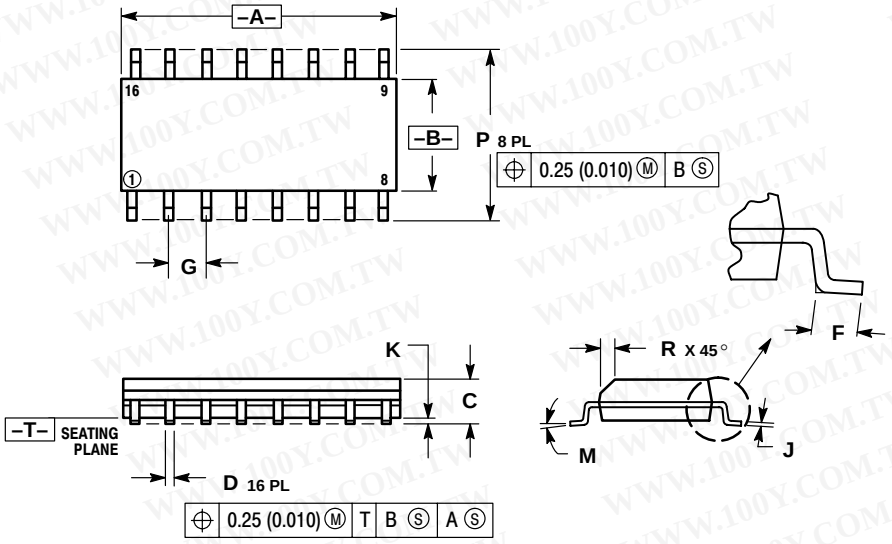
PDIP–16
N SUFFIX
16 PIN PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SO–16
D SUFFIX
16 PIN PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

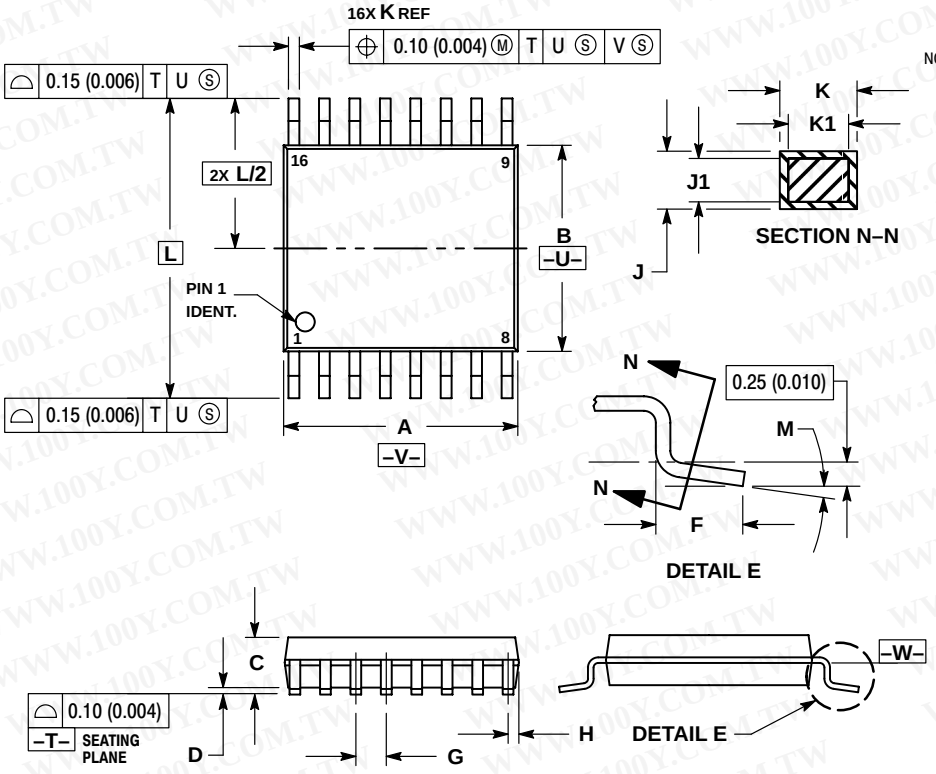


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

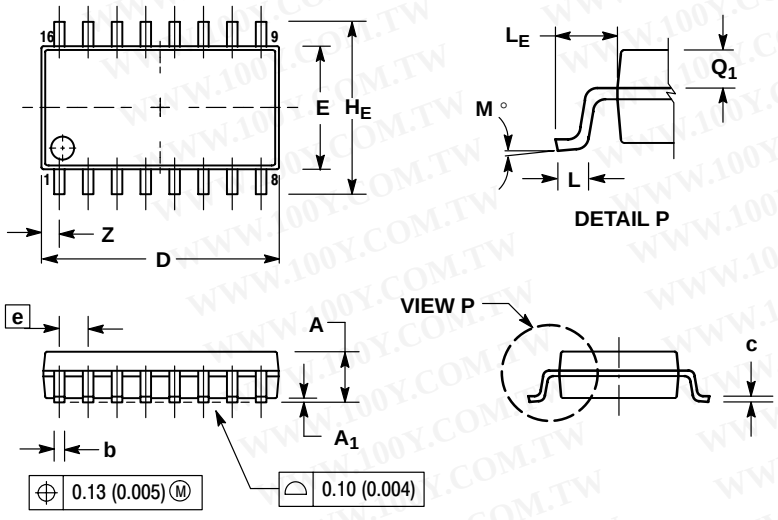
TSSOP–16
DT SUFFIX
16 PIN PLASTIC TSSOP PACKAGE
CASE948F–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

EIAJ–16
M SUFFIX
16 PIN PLASTIC EIAJ PACKAGE
CASE966–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031